

V_{DSM} = 6500 V
 I_{TAVM} = 1800 A
 I_{TRMS} = 2820 A
 I_{TSM} = 32000 A
 V_{TO} = 1.2 V
 r_T = 0.43 mΩ

Phase Control Thyristor

5STP 18M6500

Doc. No. 5SYA1010-03 Jan. 02

- Patented free-floating silicon technology
- Low on-state and switching losses
- Designed for traction, energy and industrial applications
- Optimum power handling capability
- Interdigitated amplifying gate

Blocking

Maximum rated values ¹⁾

Symbol	Conditions	5STP 18M6500	5STP 18M6200	5STP 18M5800
V_{DSM}, V_{RSM}	$f = 5 \text{ Hz}, t_p = 10\text{ms}$	6500 V	6200 V	5800 V
V_{DRM}, V_{RRM}	$f = 50 \text{ Hz}, t_p = 10\text{ms}$	5600 V	5300 V	4900 V
V_{RSM1}	$t_p = 5\text{ms}, \text{single pulse}$	7000 V	6700 V	6300 V
dV/dt_{crit}	Exp. to $0.67 \times V_{DRM}, T_j = 125^\circ\text{C}$		2000 V/ μs	

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Forward leakage current	I_{DSM}	$V_{DSM}, T_j = 125^\circ\text{C}$			600	mA
Reverse leakage current	I_{RSM}	$V_{RSM}, T_j = 125^\circ\text{C}$			600	mA

V_{DRM}/V_{RRM} are equal to V_{DSM}/V_{RSM} values up to $T_j = 110^\circ\text{C}$

Mechanical data

Maximum rated values ¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Mounting force	F_M		63	70	84	kN
Acceleration	a	Device unclamped			50	m/s^2
Acceleration	a	Device clamped			100	m/s^2

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Weight	m			1.85		kg
Surface creepage distance	D_S		45			mm
Air strike distance	D_a		21			mm

¹⁾ Maximum Ratings are those values beyond which damage to the device may occur

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On-state*Maximum rated values¹⁾*

Parameter	Symbol	Conditions	min	typ	max	Unit
Max. average on-state current	I _{TAVM}	Half sine wave, T _c = 70°C			1800	A
RMS on-state current	I _{TRMS}				2820	A
Max. peak non-repetitive surge current	I _{TSM}	tp = 10 ms, T _j = 125°C, V _D =V _R = 0 V			32000	A
Limiting load integral	I ² t				5120	kA ² s
Max. peak non-repetitive surge current	I _{TSM}	tp = 8.3 ms, T _j = 125°C, V _D =V _R =0 V			35000	A
Limiting load integral	I ² t				5000	kA ² s

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
On-state voltage	V _T	I _T = 1600 A, T _j = 125°C			1.9	V
Threshold voltage	V _{T0}	I _T = 1000 A - 3000 A, T _j = 125°C			1.2	V
Slope resistance	r _T	T _j = 125°C			0.43	mΩ
Holding current	I _H	T _j = 25°C			125	mA
		T _j = 125°C			75	mA
Latching current	I _L	T _j = 25°C			500	mA
		T _j = 125°C			250	mA

Switching*Maximum rated values¹⁾*

Parameter	Symbol	Conditions	min	typ	max	Unit
Critical rate of rise of on-state current	di/dt _{crit}	T _j = 125°C, I _{TRM} = 2000 A, V _D ≤ 0.67·V _{DRM} , I _{FG} = 2 A, t _r = 0.5 μs	Cont. f = 50 Hz		250	A/μs
Critical rate of rise of on-state current	di/dt _{crit}		Cont. f = 1Hz		1000	A/μs
Circuit-commutated turn-off time	t _q	T _j = 125°C, I _{TRM} = 2000 A, V _R = 200 V, di _T /dt = -1 A/μs, V _D ≤ 0.67·V _{DRM} , dv _D /dt = 20 V/μs,	800			μs

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Recovery charge	Q _{rr}	T _j = 125°C, I _{TRM} = 2000 A, V _R = 200 V, di _T /dt = -1 A/μs	2000		3000	μAs
Delay time	t _d	V _D = 0.4·V _{DRM} , I _{FG} = 2 A, t _r = 0.5 μs			3	μs

Triggering

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Peak forward gate voltage	V_{FGM}				12	V
Peak forward gate current	I_{FGM}				10	A
Peak reverse gate voltage	V_{RGM}				10	V
Gate power loss	P_G	For DC gate current			3	W
Average gate power loss	P_{GAV}		see Fig. 9			

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Gate trigger voltage	V_{GT}	$T_j = 25^\circ C$			2.6	V
Gate trigger current	I_{GT}	$T_j = 25^\circ C$			400	mA
Gate non-trigger voltage	V_{GD}	$V_D = 0.4 \times V_{DRM}, T_{vjmax} = 125^\circ C$	0.3			V
Gate non-trigger current	I_{GD}	$V_D = 0.4 \times V_{DRM}, T_{vjmax} = 125^\circ C$	10			mA

Thermal

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Operating junction temperature range	T_j				125	°C
Storage temperature range	T_{stg}		-40		140	°C

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Thermal resistance junction to case	$R_{th(j-c)}$	Double side cooled			9	K/kW
	$R_{th(j-c)A}$	Anode side cooled			18	K/kW
	$R_{th(j-c)C}$	Cathode side cooled			18	K/kW
Thermal resistance case to heatsink	$R_{th(c-h)}$	Double side cooled			1.5	K/kW
	$R_{th(c-h)}$	Single side cooled			3	K/kW

Analytical function for transient thermal impedance:

$$Z_{thJC}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

i	1	2	3	4
$R_i(K/kW)$	6.28	1.07	1.09	0.52
$\tau_i(s)$	0.8956	0.1606	0.0256	0.0093

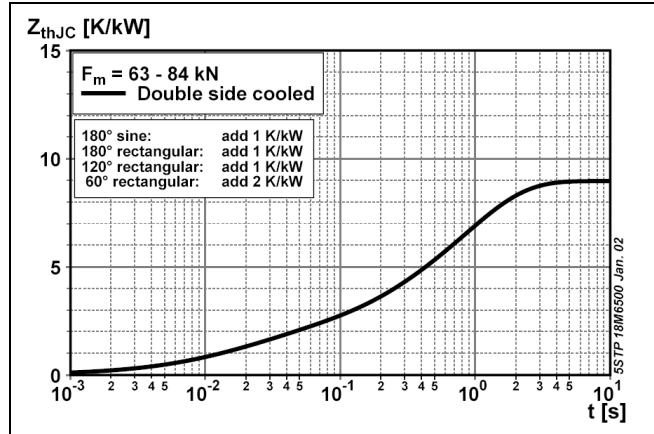


Fig. 1 Transient thermal impedance junction-to case.

On-state characteristic model:

$$VT = A + B \cdot iT + C \cdot \ln(iT + 1) + D \cdot \sqrt{iT}$$

Valid for $i_T = 400 - 6000$ A

A	B	C	D
8.7142e-1	9.3000e-5	-2.0798e-2	2.5657e-2

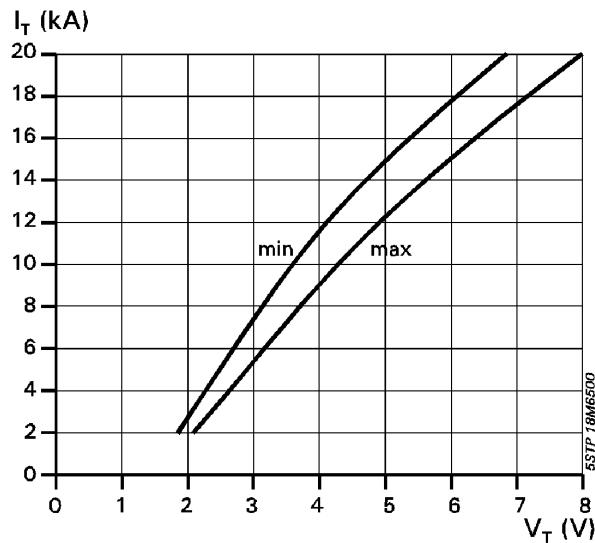


Fig. 2 On-state characteristics.
 $T_j=125^\circ\text{C}$, 10ms half sine

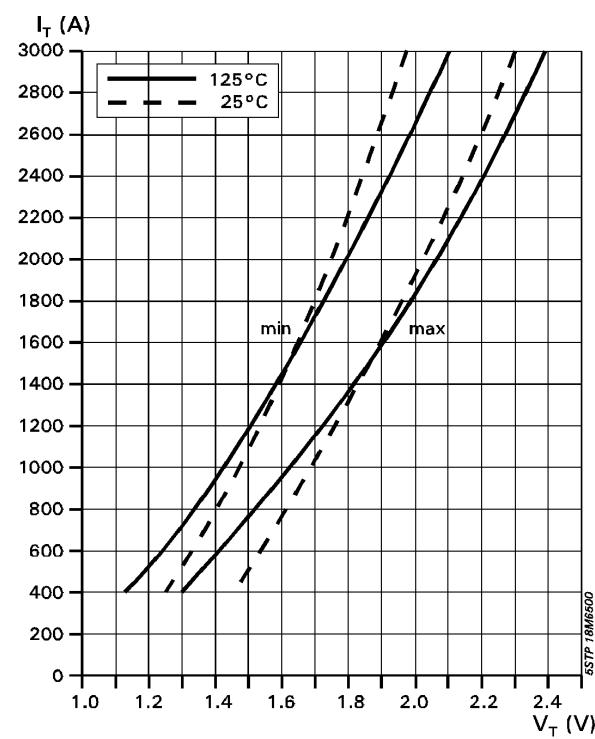


Fig. 3 On-state characteristics.

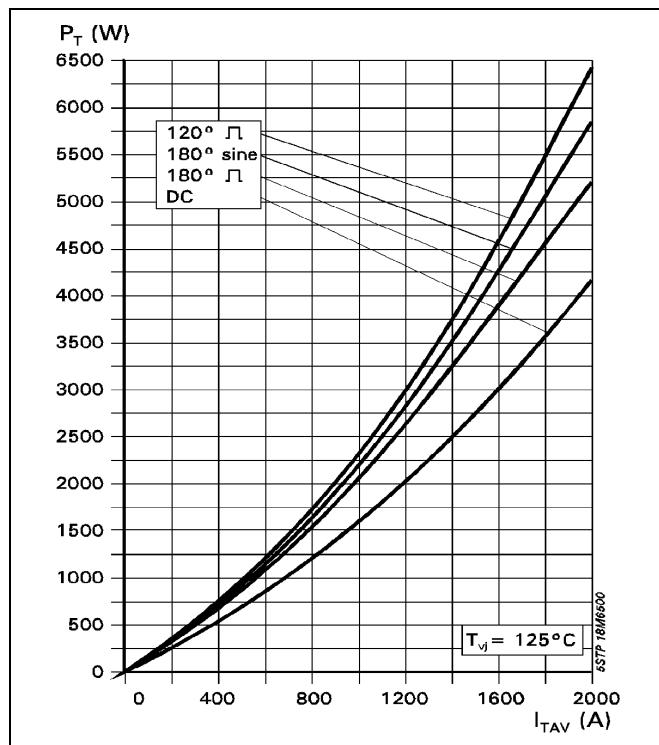


Fig. 4 On-state power dissipation vs. mean on-state current. Turn - on losses excluded.

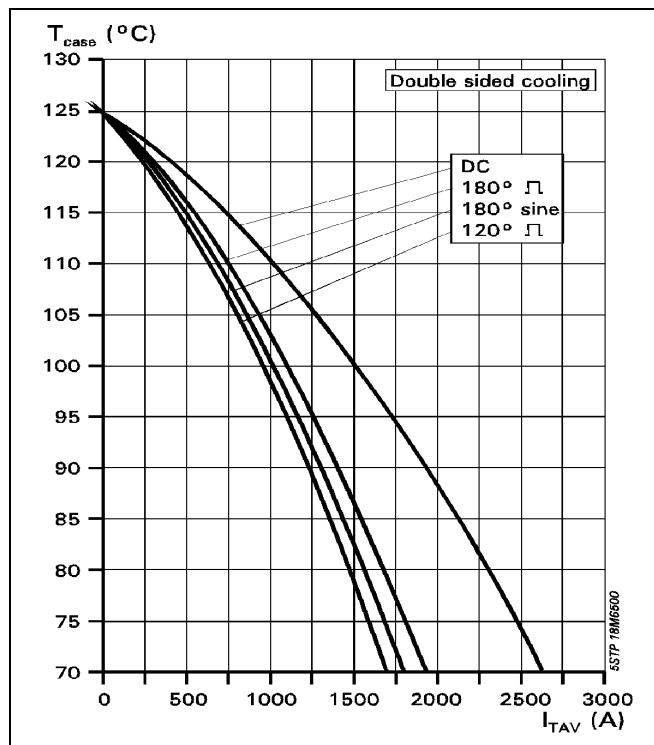


Fig. 5 Max. permissible case temperature vs. mean on-state current.

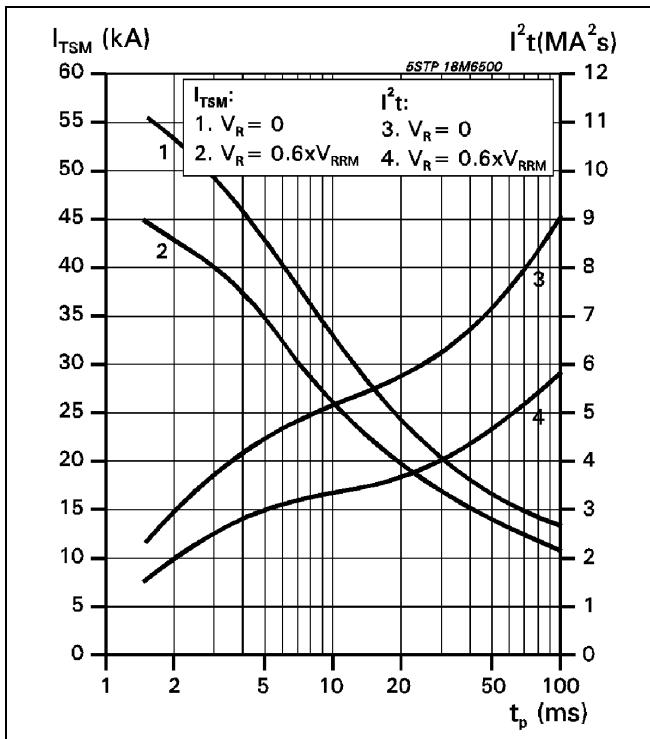


Fig. 6 Surge on-state current vs. pulse length. Half-sine wave.

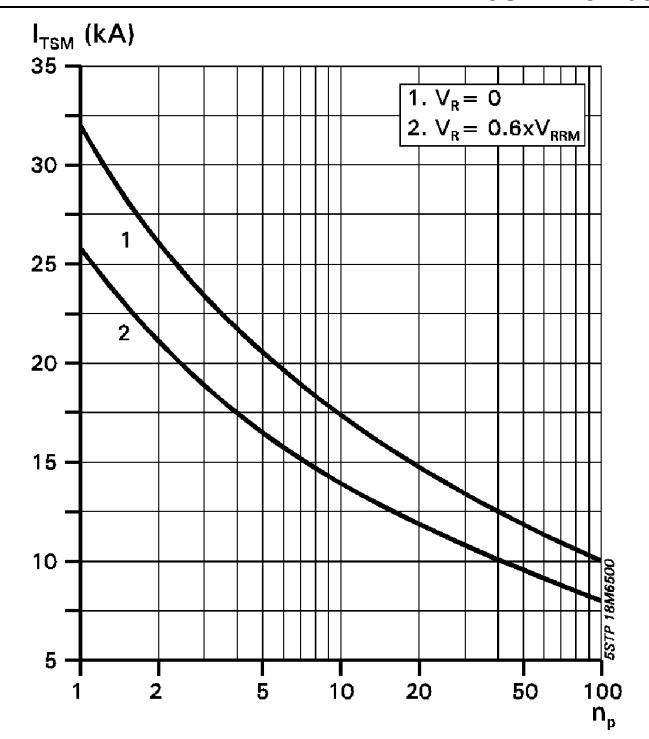


Fig. 7 Surge on-state current vs. number of pulses. Half-sine wave, 10 ms, 50Hz.

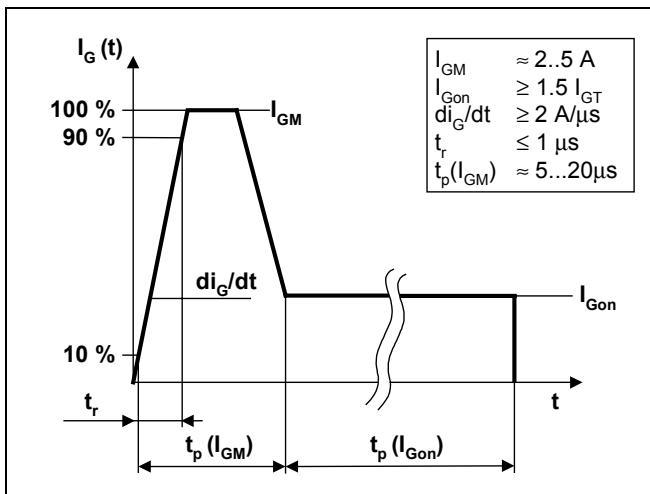


Fig. 8 Recommended gate current waveform.

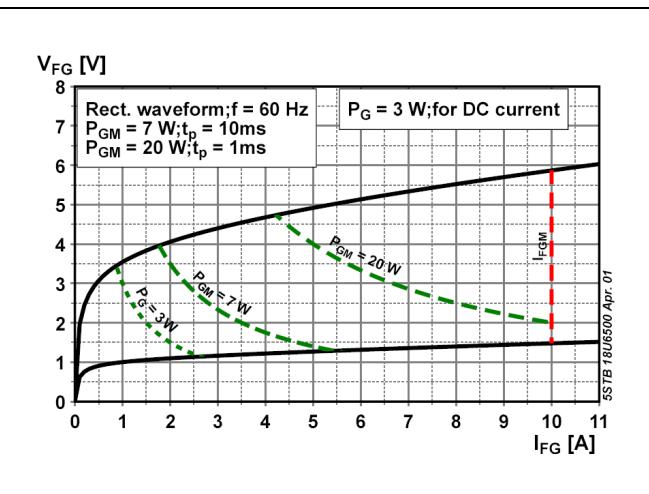


Fig. 9 Max. peak gate power loss.

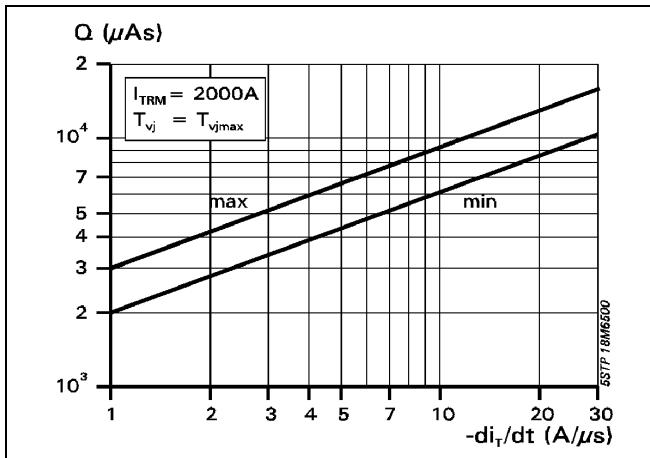


Fig. 10 Recovery charge vs. decay rate of on-state current.

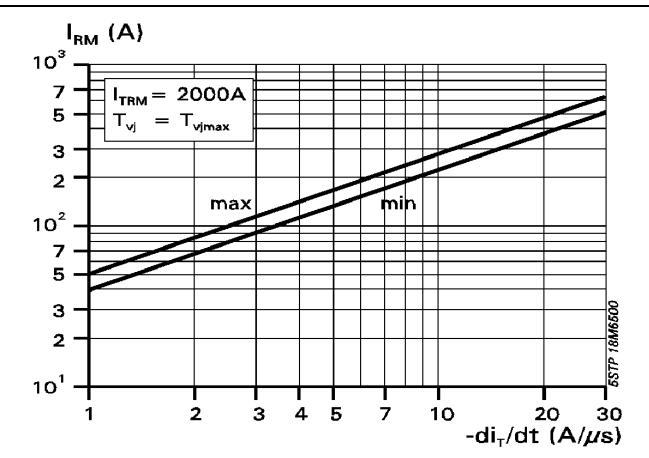


Fig. 11 Peak reverse recovery current vs. decay rate of on-state current.

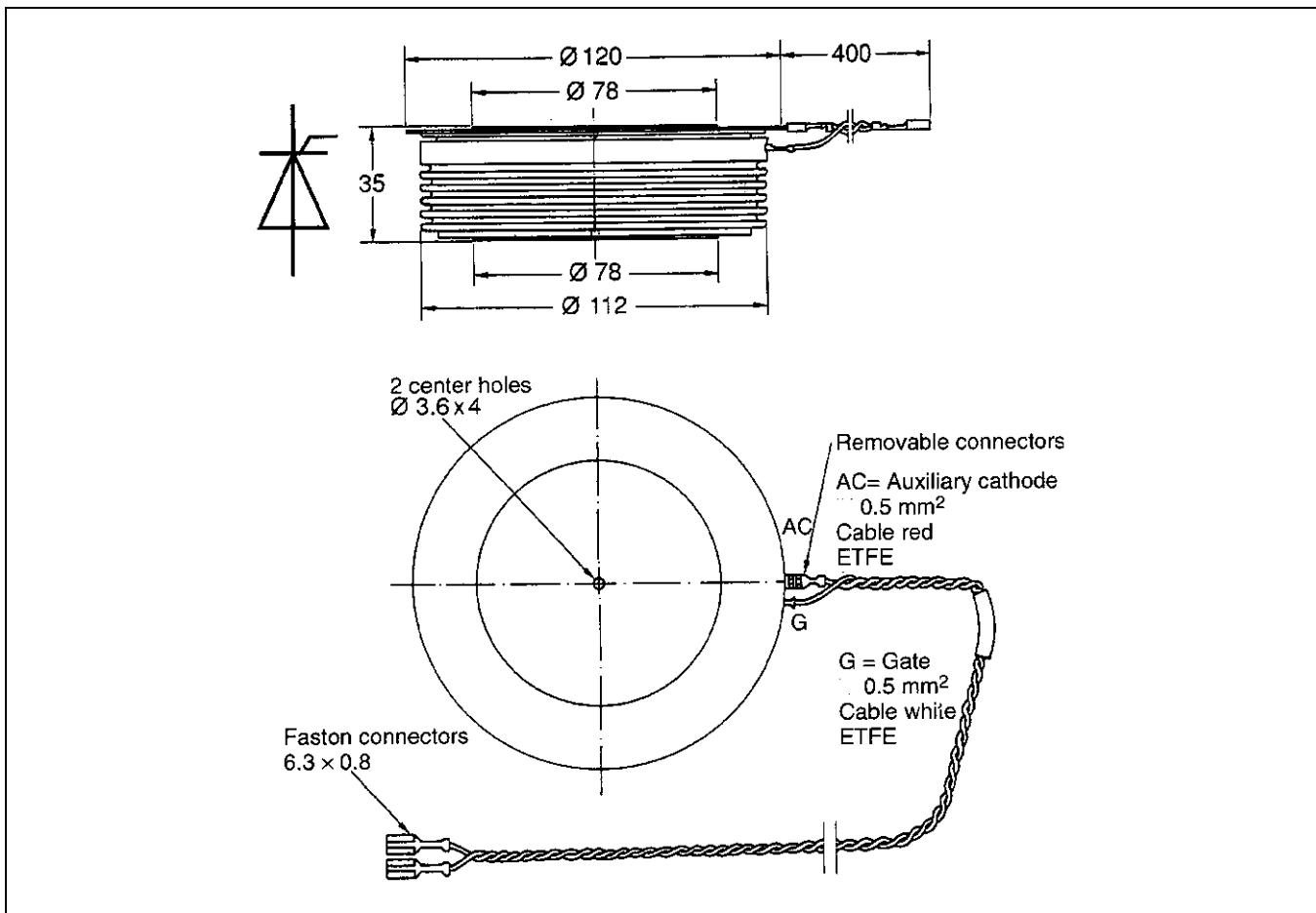


Fig. 12 Device Outline Drawing.

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